

$V_{DRM}$	=	5200 V
$I_{T(AV)M}$	=	3450 A
$I_{T(RMS)}$	=	5420 A
$I_{TSM}$	=	$63.0 \cdot 10^3$ A
$V_{TO}$	=	0.96 V
$r_T$	=	0.194 mΩ

# Phase Control Thyristor

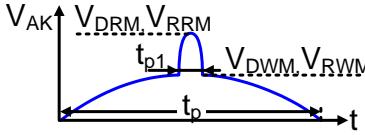
**5STP 34N5200**

Doc. No. 5SYA1002-08 Mar. 20

- Patented free-floating silicon technology
- Low on-state and switching losses
- Designed for traction, energy and industrial applications
- Optimum power handling capability
- Interdigitated amplifying gate

## Blocking

*Maximum rated values <sup>1)</sup>*

Parameter	Symbol	Conditions	5STP 34N5200		Unit
Max. surge peak forward and reverse blocking voltage	$V_{DSM}, V_{RSM}$	$t_p = 10$ ms, $f = 5$ Hz $T_{vj} = 5 \dots 125$ °C, Note 1	5200		V
Max repetitive peak forward and reverse blocking voltage	$V_{DRM}, V_{RRM}$	$f = 50$ Hz, $t_p = 10$ ms, $t_{p1} = 250$ µs, $T_{vj} = 5 \dots 125$ °C, Note 1, Note 2	5200		V
Max crest working forward and reverse voltages	$V_{DWM}, V_{RWM}$		3470		V
Critical rate of rise of commutating voltage	$dv/dt_{crit}$	Exp. to $0.67 \cdot V_{DRM}$ , $T_{vj} = 125$ °C	2000		V/µs

*Characteristic values*

Parameter	Symbol	Conditions	min	typ	max	Unit
Forward leakage current	$I_{DRM}$	$V_{DRM}$ , $T_{vj} = 125$ °C			500	mA
Reverse leakage current	$I_{RRM}$	$V_{RRM}$ , $T_{vj} = 125$ °C			500	mA

Note 1: Voltage de-rating factor of 0.11% per °C is applicable for  $T_{vj}$  below +5 °C.

Note 2: Recommended minimum ratio of  $V_{DRM} / V_{DWM}$  or  $V_{RRM} / V_{RWM} = 2$ . See App. Note 5SYA 2051.

## Mechanical data

*Maximum rated values <sup>1)</sup>*

Parameter	Symbol	Conditions	min	typ	max	Unit
Mounting force	$F_M$		81	90	108	kN
Acceleration	a	Device unclamped			50	m/s <sup>2</sup>
Acceleration	a	Device clamped			100	m/s <sup>2</sup>

*Characteristic values*

Parameter	Symbol	Conditions	min	typ	max	Unit
Weight	m				2.9	kg
Housing thickness	H	$F_M = 90$ kN, $T_a = 25$ °C	34.75		35.40	mm
Surface creepage distance	D <sub>s</sub>		56			mm
Air strike distance	D <sub>a</sub>		22			mm

1) Maximum rated values indicate limits beyond which damage to the device may occur

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**On-state****Maximum rated values<sup>1)</sup>**

Parameter	Symbol	Conditions	min	typ	max	Unit
Average on-state current	I <sub>T(AV)M</sub>	Half sine wave, T <sub>c</sub> = 70 °C			3450	A
RMS on-state current	I <sub>T(RMS)</sub>				5420	A
Peak non-repetitive surge current	I <sub>TSM</sub>	t <sub>p</sub> = 10 ms, T <sub>vj</sub> = 125 °C, sine half wave,			63.0·10 <sup>3</sup>	A
Limiting load integral	I <sup>2</sup> t	V <sub>D</sub> = V <sub>R</sub> = 0 V, after surge			19.8·10 <sup>6</sup>	A <sup>2</sup> s
Peak non-repetitive surge current	I <sub>TSM</sub>	t <sub>p</sub> = 10 ms, T <sub>vj</sub> = 125 °C, sine half wave,			45.5·10 <sup>3</sup>	A
Limiting load integral	I <sup>2</sup> t	V <sub>R</sub> = 0.6·V <sub>RRM</sub> , after surge			10.3·10 <sup>6</sup>	A <sup>2</sup> s

**Characteristic values**

Parameter	Symbol	Conditions	min	typ	max	Unit
On-state voltage	V <sub>T</sub>	I <sub>T</sub> = 3000 A, T <sub>vj</sub> = 125 °C		1.47	1.54	V
Threshold voltage	V <sub>(TO)</sub>				0.96	V
Slope resistance	r <sub>T</sub>	I <sub>T</sub> = 2300 A - 7000 A, T <sub>vj</sub> = 125 °C			0.194	mΩ
Holding current	I <sub>H</sub>	T <sub>vj</sub> = 25 °C			125	mA
		T <sub>vj</sub> = 125 °C			75	mA
Latching current	I <sub>L</sub>	T <sub>vj</sub> = 25 °C			500	mA
		T <sub>vj</sub> = 125 °C			250	mA

**Switching****Maximum rated values<sup>1)</sup>**

Parameter	Symbol	Conditions	min	typ	max	Unit
Critical rate of rise of on-state current	di/dt <sub>crit</sub>	T <sub>vj</sub> = 125 °C, I <sub>T</sub> = 3000 A, V <sub>D</sub> ≤ 0.67·V <sub>RRM</sub> , I <sub>GM</sub> = 2 A, t <sub>r</sub> = 0.5 μs	Cont. f = 50 Hz			250 A/μs
			Cont. f = 1 Hz			1000 A/μs
Circuit-commutated turn-off time	t <sub>q</sub>	T <sub>vj</sub> = 125 °C, I <sub>T</sub> = 2000 A, V <sub>R</sub> = 200 V, di <sub>T</sub> /dt = -1.5 A/μs, V <sub>D</sub> ≤ 0.67·V <sub>RRM</sub> , dv <sub>D</sub> /dt = 20 V/μs			700	μs

**Characteristic values**

Parameter	Symbol	Conditions	min	typ	max	Unit
Reverse recovery charge	Q <sub>rr</sub>	T <sub>vj</sub> = 125 °C, I <sub>T</sub> = 2000 A,	3400	4770	5200	μAs
Reverse recovery current	I <sub>RM</sub>	V <sub>R</sub> = 200 V, di <sub>T</sub> /dt = -1.5 A/μs	60	77	95	A
Gate turn-on delay time	t <sub>gd</sub>	T <sub>vj</sub> = 25 °C, V <sub>D</sub> = 0.4·V <sub>RRM</sub> , I <sub>GM</sub> = 2 A, t <sub>r</sub> = 0.5 μs			3	μs

## Triggering

*Maximum rated values<sup>1)</sup>*

Parameter	Symbol	Conditions	min	typ	max	Unit
Peak forward gate voltage	V <sub>FGM</sub>				12	V
Peak forward gate current	I <sub>FGM</sub>				10	A
Peak reverse gate voltage	V <sub>RGM</sub>				10	V
Average gate power loss	P <sub>G(AV)</sub>				see Fig. 7	W

*Characteristic values*

Parameter	Symbol	Conditions	min	typ	max	Unit
Gate-trigger voltage	V <sub>GT</sub>	T <sub>vj</sub> = 25 °C			2.6	V
Gate-trigger current	I <sub>GT</sub>	T <sub>vj</sub> = 25 °C			400	mA
Gate non-trigger voltage	V <sub>GD</sub>	V <sub>D</sub> = 0.4 · V <sub>DRM</sub> , T <sub>vjmax</sub> = 125 °C			0.3	V
Gate non-trigger current	I <sub>GD</sub>	V <sub>D</sub> = 0.4 · V <sub>DRM</sub> , T <sub>vjmax</sub> = 125 °C			10	mA

## Thermal

*Maximum rated values<sup>1)</sup>*

Parameter	Symbol	Conditions	min	typ	max	Unit
Operating junction temperature range	T <sub>vj</sub>				125	°C
Storage temperature range	T <sub>stg</sub>		-40		140	°C

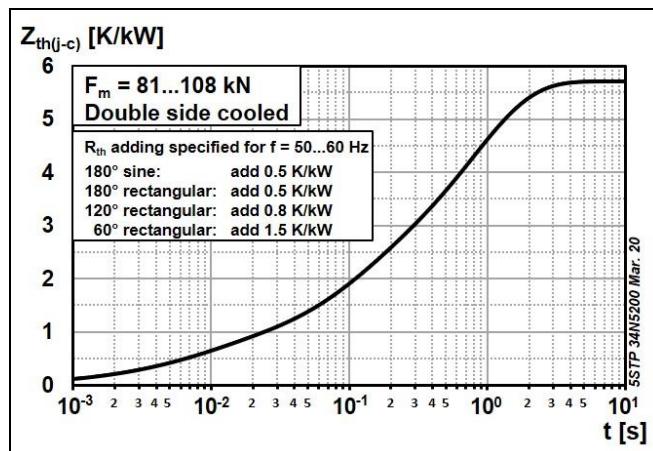
*Characteristic values*

Parameter	Symbol	Conditions	min	typ	max	Unit
Thermal resistance junction to case	R <sub>th(j-c)</sub>	Double-side cooled F <sub>m</sub> = 81... 108 kN			5.7	K/kW
	R <sub>th(j-c)A</sub>	Anode-side cooled F <sub>m</sub> = 81... 108 kN			11.4	K/kW
	R <sub>th(j-c)C</sub>	Cathode-side cooled F <sub>m</sub> = 81... 108 kN			11.4	K/kW
Thermal resistance case to heatsink	R <sub>th(c-h)</sub>	Double-side cooled F <sub>m</sub> = 81... 108 kN			1	K/kW
	R <sub>th(c-h)</sub>	Single-side cooled F <sub>m</sub> = 81... 108 kN			2	K/kW

**Analytical function for transient thermal impedance:**

$$Z_{th(j-c)}(t) = \sum_{i=1}^n R_i (1 - e^{-t/\tau_i})$$

i	1	2	3	4
R <sub>i</sub> (K/kW)	3.837	1.254	0.561	0.048
τ <sub>i</sub> (s)	0.7934	0.0893	0.0072	0.0012



**Fig. 1** Transient thermal impedance (junction-to-case) vs. time

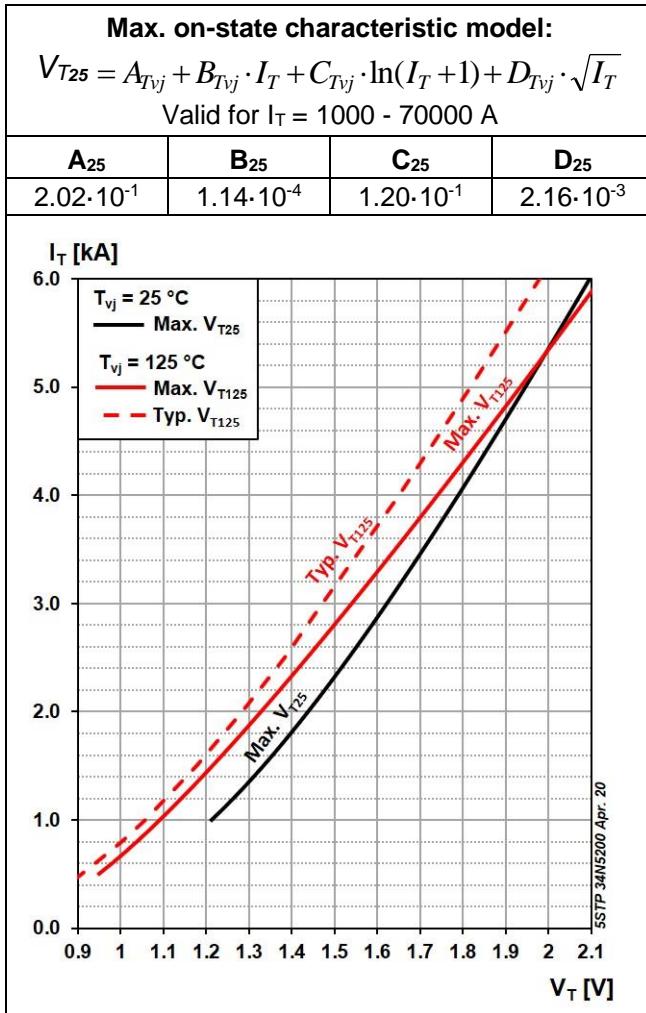


Fig. 2 On-state voltage characteristics

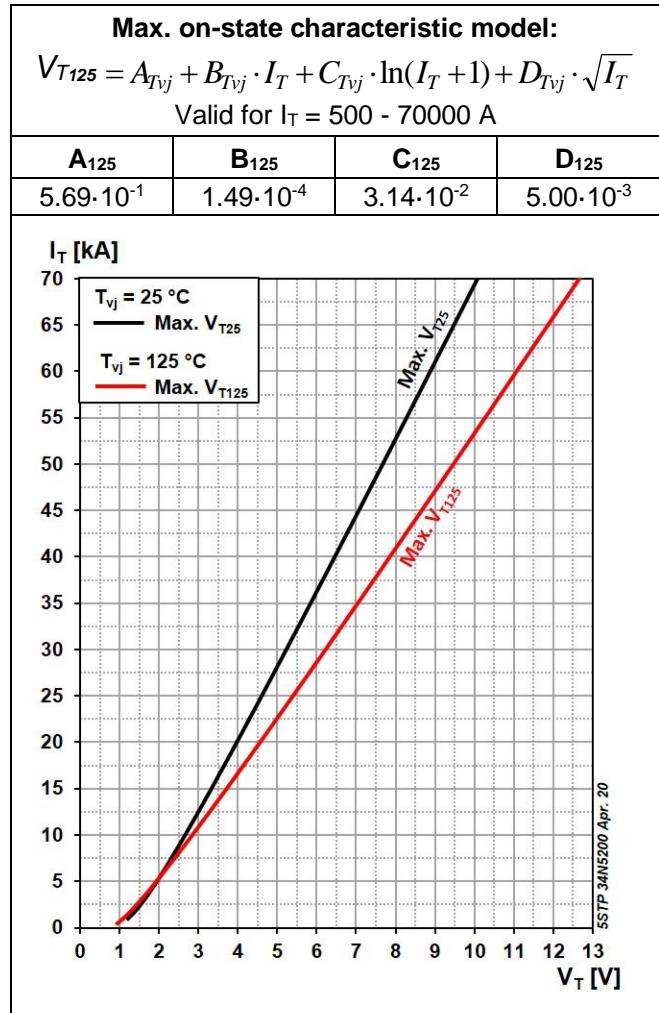


Fig. 3 On-state voltage characteristics

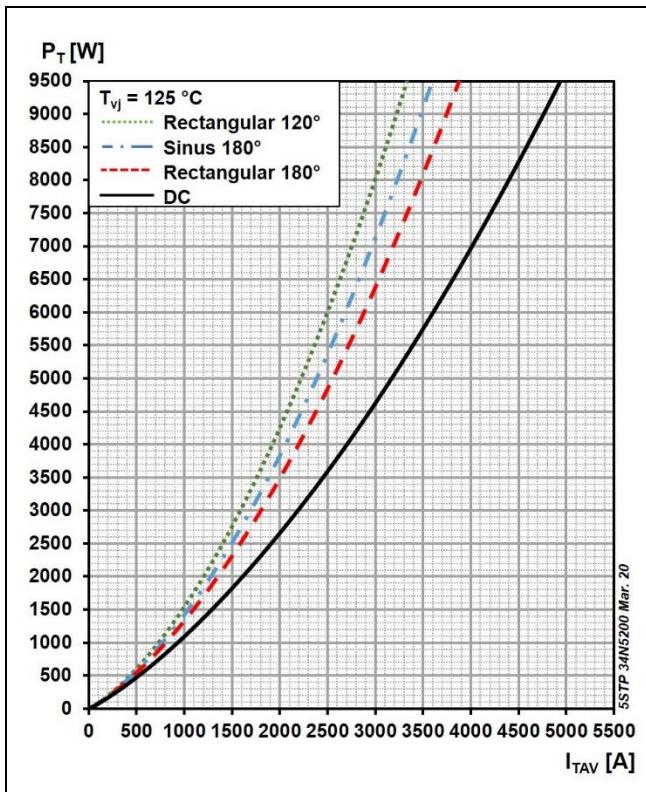


Fig. 4 On-state power dissipation vs. mean on-state current, turn-on losses excluded

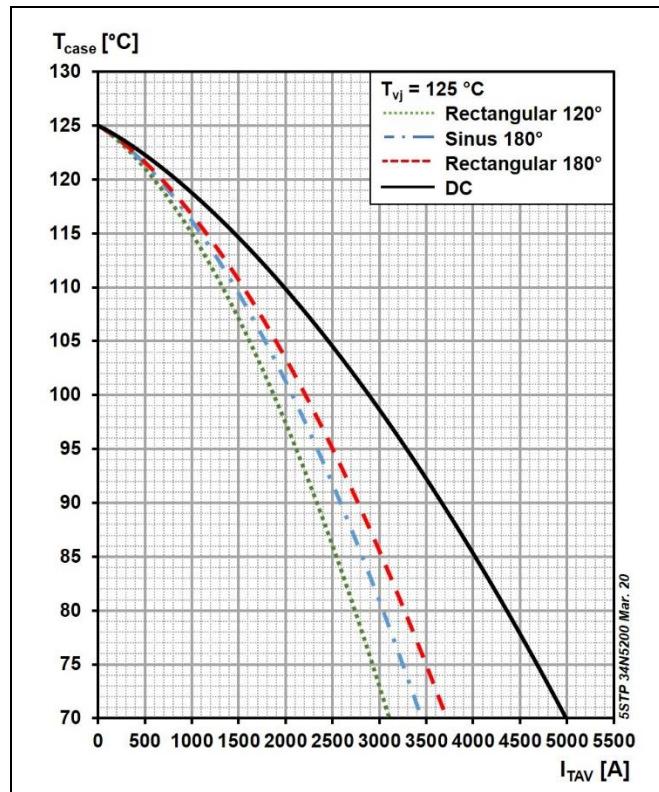
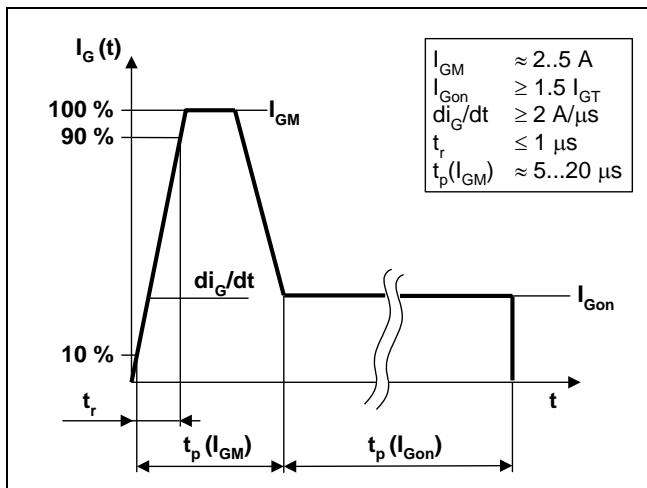
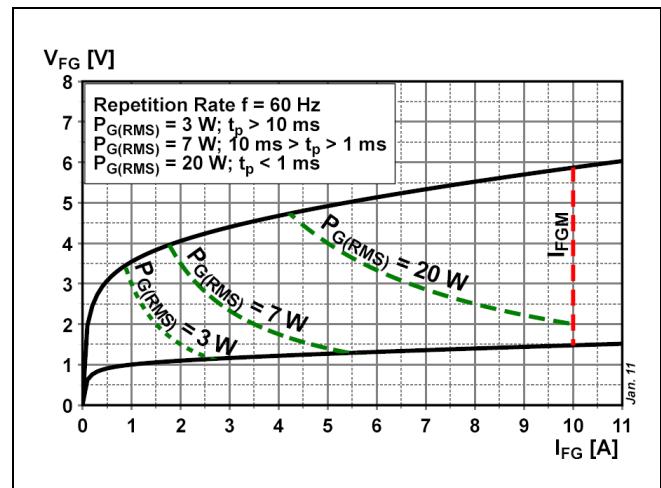
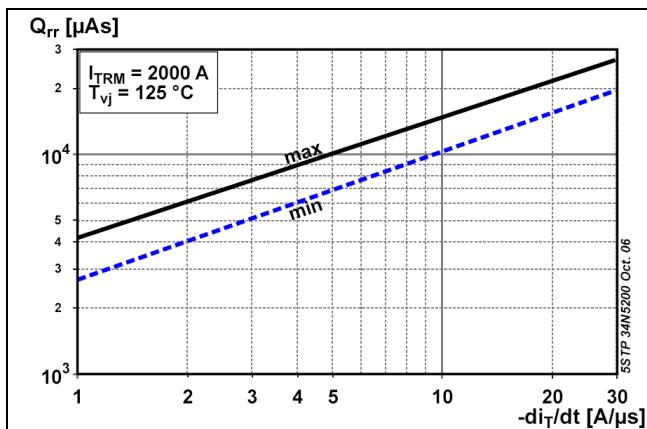
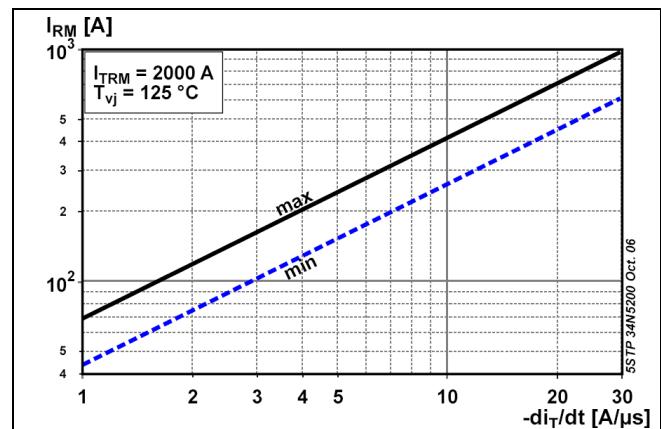


Fig. 5 Max. permissible case temperature vs. mean on-state current, switching losses ignored

**Fig. 6** Recommended gate current waveform**Fig. 7** Max. peak gate power loss**Fig. 8** Reverse recovery charge vs. decay rate of on-state current**Fig. 9** Peak reverse recovery current vs. decay rate of on-state current

## Turn-on and Turn-off losses

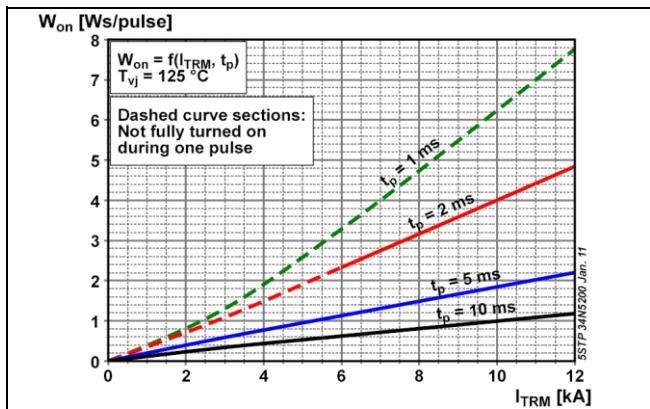


Fig. 10 Turn-on energy, half sinusoidal waves

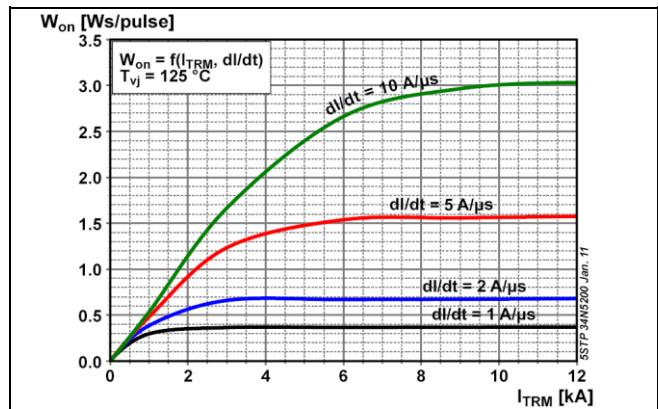


Fig. 11 Turn-on energy, rectangular waves

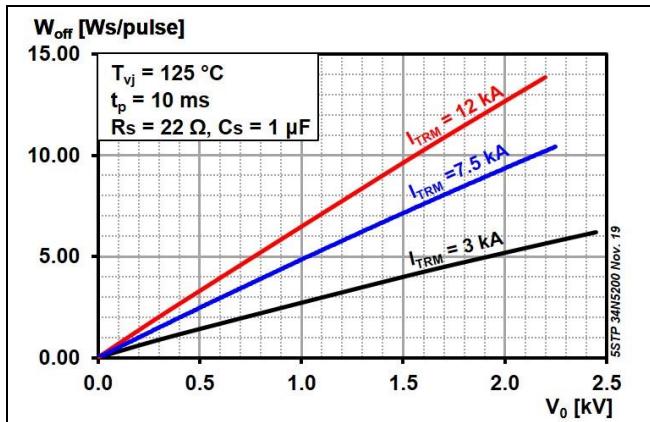


Fig. 12 Typical turn-off energy, half sinusoidal waves

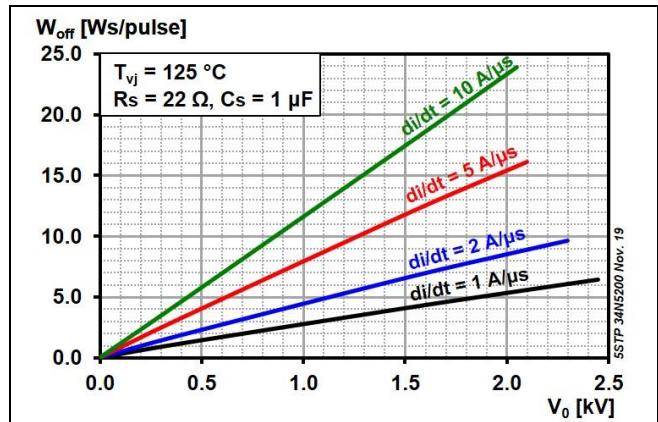


Fig. 13 Typical turn-off energy, rectangular waves

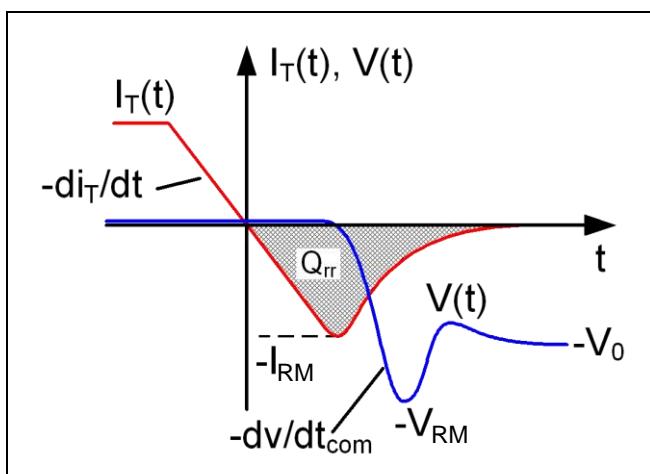


Fig. 14 Current and voltage waveforms at turn-off

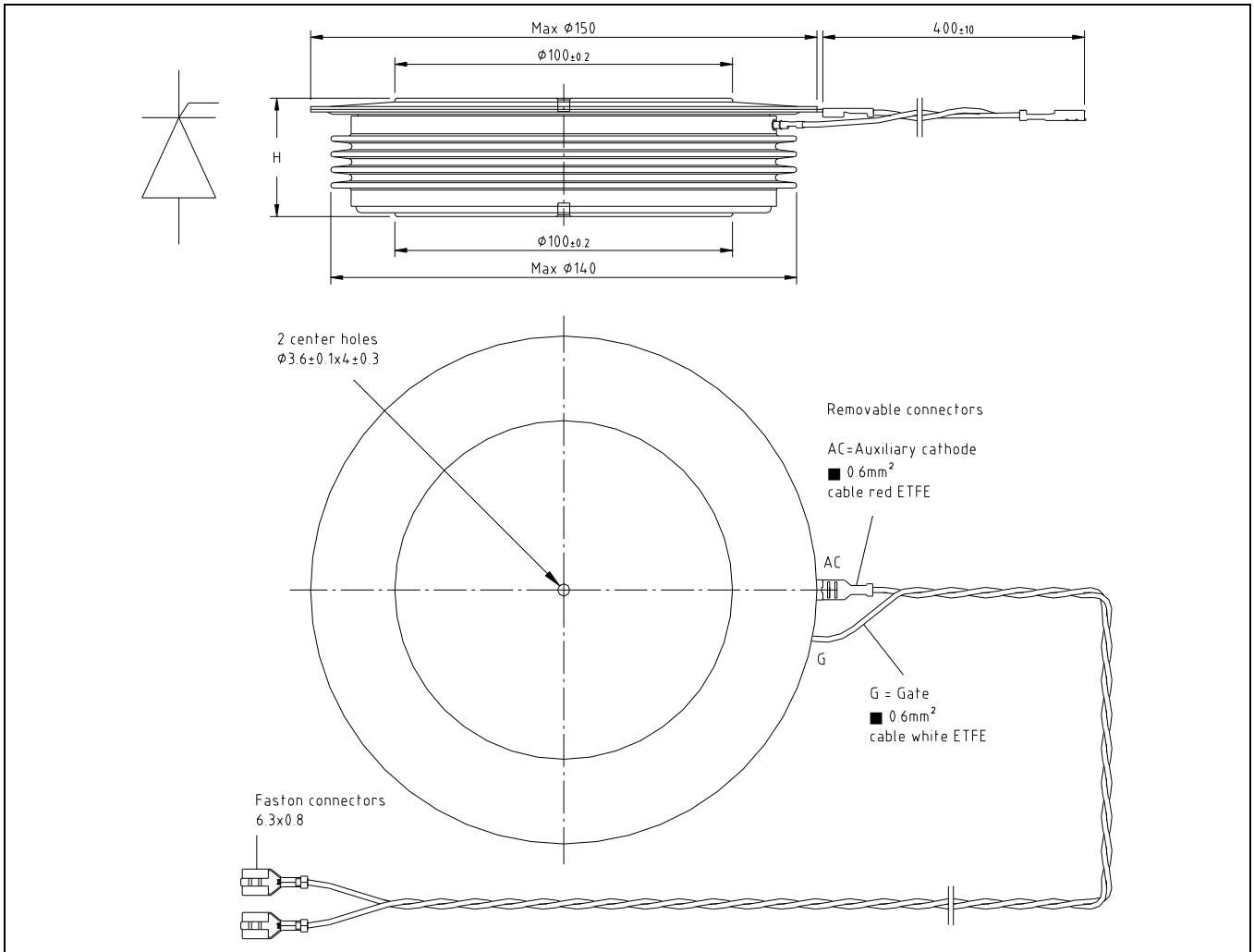
**Total power loss for repetitive waveforms:**

$$P_{TOT} = P_T + W_{on} \cdot f + W_{off} \cdot f$$

where

$$P_T = \frac{1}{T} \int_0^T I_T \cdot V_T(I_T) dt$$

Fig. 15 Relationships for power loss



**Fig. 16** Device Outline Drawing

### Related documents:

- |           |   |
|-----------|---|
| 5SYA 2020 | Design of RC-Snubbers for Phase Control Applications                                    |
| 5SYA 2049 | Voltage definitions for phase control and bi-directionally controlled thyristors        |
| 5SYA 2051 | Voltage ratings of high power semiconductors  |
| 5SYA 2034 | Gate-drive recommendations for phase control and bi-directionally controlled thyristors |
| 5SYA 2036 | Recommendations regarding mechanical clamping of Press-Pack High Power Semiconductors   |
| 5SYA 2102 | Surge currents for Phase Control Thyristors   |
| 5SJK 9118 | General Environmental Conditions for High Power Semiconductors                          |

Please refer to <http://www.abb.com/semiconductors> for current version of documents.

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